



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1908-03	DATE: 12-Sep-2019	MEANS OF DISTINGUISHING CHANGED DEVICES:
Product Affected: DFN-10 (Refer to Attachment II for the affected part#)		☐ Product Mark Lot # will have: ☒ Back Mark "MS" prefix for Carsem, Malaysia (S ☐ Date Code site) ☐ Other
Date Effective: 12-Dec-2019		
Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No	
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request.	

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|--|
| ☐ Die Technology | |
| ☐ Wafer Fabrication Process | This notification is to advise our customers that IDT is adding Carsem, Malaysia (S site) as an alternate assembly facility. |
| ☐ Assembly Process | |
| ☐ Equipment | |
| ☒ Material | There is no change to the moisture performance. |
| ☐ Testing | |
| ☒ Manufacturing Site | Attachment I details the qualification results. |
| ☐ Data Sheet | |
| ☐ Other | |

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ Approval for shipments prior to effective date.
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

PRODUCT/PROCESS CHANGE NOTICE (PCN)**ATTACHMENT I - PCN # : A1908-03****PCN Type:** Alternate Assembly Location & Change Material Sets**Data Sheet Change:** None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding Carsem, Malaysia (S site) as an alternate assembly facility.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance rating but the material declaration will differ.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

	Existing	Alternate
Material Set / Assembly	UTL - UTAC, Thailand	CRSS - Carsem, Malaysia (S site)
Die Attach	8200T, 8006NS	QMI519
Bonding Wire	Copper wire	Copper wire
Mold Compound	G700LTD	G770HCD

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ATTACHMENT I - PCN # : A1908-03

Qualification Information and Qualification Data:

Affected Packages: DFN-10

Assembly Material: Shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: DFN-10

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
X-Ray Examination	IDT Spec. MAC-3012	0/45	0/45	0/45
Ball Shear Test	JESD22-B117	0/5	0/5	0/5
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 1, 260 °C	0/25	0/25	-

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



A Renesas Company

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT II - PCN # : A1908-03

Affected Part Numbers

Part Number	Part Number	Part Number
5PB1203NTGK	5PB1213NTGK	5V30202NTGI
5PB1203NTGK8	5PB1213NTGK8	5V30202NTGI8